

YJ Planar Schottky Barrier Diode Die Specification

200V 60A, 230mil, Schottky barrier diode die based on silicon planar process
Part No.: PSB230S200AS-290F

Main Products Characterstics

Forward Voltage	200V
Reverse Current	100μA
Forward Resistance	3.3mΩ
Reverse Resistance	100kΩ
Capacitance	100pF
Power Dissipation	10W
Temperature Coefficient	±0.5%
Storage Temperature	-55℃~150℃
Operating Temperature	-55℃~150℃
Maximum Junction Temperature	175℃
Die Thickness	230mil
Die Size	1.5mm x 1.5mm
Top Metal Pad	0.5mm x 0.5mm
Active Area	0.5mm x 0.5mm
Top Metal	0.5mm x 0.5mm
Back Metal	0.5mm x 0.5mm

Maximum Ratings

Maximum Forward Current	60A
Maximum Reverse Current	100μA
Maximum Forward Voltage	200V
Maximum Reverse Voltage	200V
Maximum Power Dissipation	10W
Maximum Junction Temperature	175℃
Maximum Storage Temperature	-55℃~150℃
Maximum Operating Temperature	-55℃~150℃
Maximum Forward Resistance	3.3mΩ
Maximum Reverse Resistance	100kΩ
Maximum Capacitance	100pF
Maximum Temperature Coefficient	±0.5%
Maximum Die Thickness	230mil
Maximum Die Size	1.5mm x 1.5mm
Maximum Top Metal Pad	0.5mm x 0.5mm
Maximum Active Area	0.5mm x 0.5mm
Maximum Top Metal	0.5mm x 0.5mm
Maximum Back Metal	0.5mm x 0.5mm

Static Electrical Characteristics (Ta = 25℃)

Forward Voltage	200V
Reverse Current	100μA
Forward Resistance	3.3mΩ
Reverse Resistance	100kΩ
Capacitance	100pF
Power Dissipation	10W
Temperature Coefficient	±0.5%
Storage Temperature	-55℃~150℃
Operating Temperature	-55℃~150℃
Maximum Junction Temperature	175℃
Die Thickness	230mil
Die Size	1.5mm x 1.5mm
Top Metal Pad	0.5mm x 0.5mm
Active Area	0.5mm x 0.5mm
Top Metal	0.5mm x 0.5mm
Back Metal	0.5mm x 0.5mm

Device Schematics and Outline Drawing

Die Thickness *	230mil
Die Size **	1.5mm x 1.5mm
Top Metal Pad	0.5mm x 0.5mm
Active Area	0.5mm x 0.5mm
Top Metal	0.5mm x 0.5mm
Back Metal	0.5mm x 0.5mm
Note: 1 *	Also can offer device with 8 mils thickness
2 **	Cutting street width is around 1.5 mils

Important Notice

Specification apply to die only. Actual performance may degrade when assembled.	Recommended Storage Environment:
does not guarantee device performance after assembly.	Store in original container, in dessicated nitrogen, with no contamination.